

# Silicon Carbide (SiC) Schottky Diode – EliteSiC, 30 A, 650 V, D2, TO-220-2L

## FFSP3065B

Silicon Carbide (SiC) Schottky Diodes use a completely new technology that provides superior switching performance and higher reliability compared to Silicon. No reverse recovery current, temperature independent switching characteristics, and excellent thermal performance sets Silicon Carbide as the next generation of power semiconductor. System benefits include highest efficiency, faster operating frequency, increased power density, reduced EMI, and reduced system size and cost.

### Features

- Max Junction Temperature 175°C
- Avalanche Rated 144 mJ
- High Surge Current Capacity
- Positive Temperature Coefficient
- Ease of Paralleling
- No Reverse Recovery / No Forward Recovery
- These Devices are Pb-Free, Halogen Free/BFR Free and are RoHS Compliant

### Applications

- General Purpose
- SMPS, Solar Inverter, UPS
- Power Switching Circuit

### ABSOLUTE MAXIMUM RATINGS

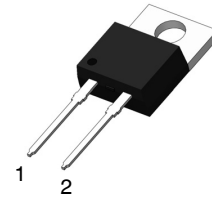
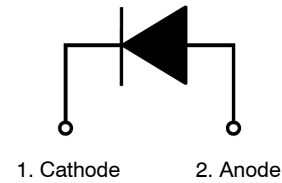
(T<sub>C</sub> = 25°C, Unless otherwise specified)

Symbol	Parameter	Value	Unit	
V <sub>RRM</sub>	Peak Repetitive Reverse Voltage	650	V	
E <sub>AS</sub>	Single Pulse Avalanche Energy (Note 1)	144	mJ	
	Continuous Rectified Forward Current @ T <sub>C</sub> < 135°C	30		
I <sub>F, Max</sub>	Non-Repetitive Peak Forward Surge Current	T <sub>C</sub> = 25°C, 10 μs	1100	A
		T <sub>C</sub> = 150°C, 10 μs	1000	
I <sub>F, SM</sub>	Non-Repetitive Forward Surge Current	Half-Sine Pulse, t <sub>p</sub> = 8.3 ms	110	A
P <sub>tot</sub>	Power Dissipation	T <sub>C</sub> = 25°C	197	W
		T <sub>C</sub> = 150°C	33	
T <sub>J</sub> , T <sub>STG</sub>	Operating and Storage Temperature Range	-55 to +175	°C	

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

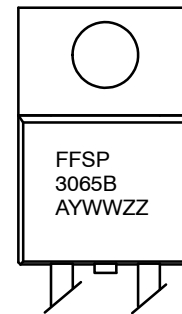
1. E<sub>AS</sub> of 144 mJ is based on starting T<sub>J</sub> = 25°C, L = 0.5 mH, I<sub>AS</sub> = 24 A, V = 50 V.

### ELECTRICAL CONNECTION



TO-220-2LD  
CASE 340BB

### MARKING DIAGRAM



FFSP3065B      = Specific Device Code  
A                = Assembly Location  
Y                = Year  
WW             = Work Week  
ZZ             = Assembly Lot Code

### ORDERING INFORMATION

See detailed ordering and shipping information in the package dimensions section on page 2 of this data sheet.

# FFSP3065B

## THERMAL CHARACTERISTICS

Symbol	Parameter	Ratings	Unit
$R_{\theta JC}$	Thermal Resistance, Junction to Case, Max.	0.76	$^{\circ}\text{C}/\text{W}$

## ELECTRICAL CHARACTERISTICS $T_C = 25^{\circ}\text{C}$ unless otherwise noted

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Unit
$V_F$	Forward Voltage	$I_F = 30\text{ A}, T_C = 25^{\circ}\text{C}$	-	1.38	1.7	V
		$I_F = 30\text{ A}, T_C = 125^{\circ}\text{C}$	-	1.6	2.0	
		$I_F = 30\text{ A}, T_C = 175^{\circ}\text{C}$	-	1.72	2.4	
$I_R$	Reverse Current	$V_R = 650\text{ V}, T_C = 25^{\circ}\text{C}$	-	0.5	40	$\mu\text{A}$
		$V_R = 650\text{ V}, T_C = 125^{\circ}\text{C}$	-	1.0	80	
		$V_R = 650\text{ V}, T_C = 175^{\circ}\text{C}$	-	2.0	160	
$Q_C$	Total Capacitive Charge	$V = 400\text{ V}$	-	74	-	nC
C	Total Capacitance	$V_R = 1\text{ V}, f = 100\text{ kHz}$	-	1280	-	pF
		$V_R = 200\text{ V}, f = 100\text{ kHz}$	-	139	-	
		$V_R = 400\text{ V}, f = 100\text{ kHz}$	-	108	-	

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

## PACKAGE MARKING AND ORDERING INFORMATION

Part Number	Top Mark	Package	Packing Method	Reel Size	Tape Width	Quantity
FFSP3065B	FFSP3065B	TO-220-2L	Tube	N/A	N/A	50 Units

TYPICAL CHARACTERISTICS  $T_J = 25^\circ\text{C}$  UNLESS OTHERWISE NOTED

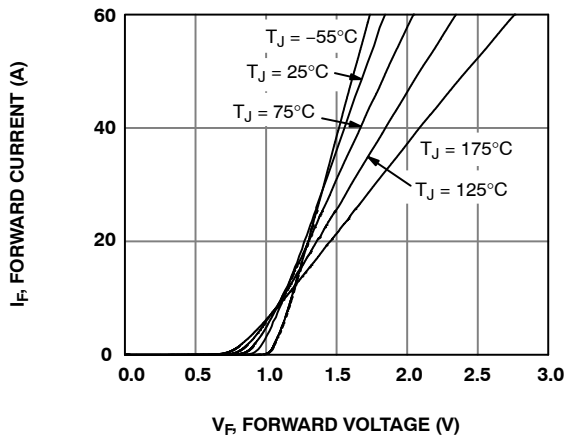


Figure 1. Forward Characteristics

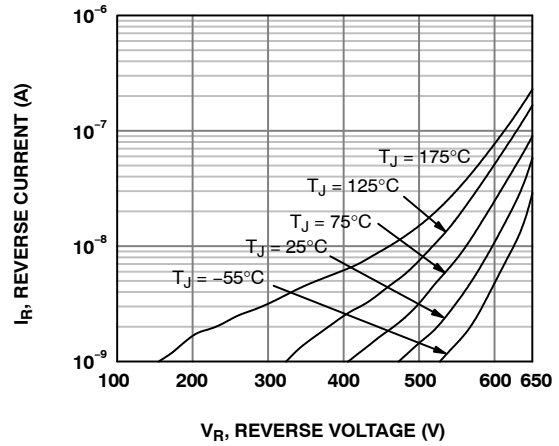


Figure 2. Reverse Characteristics

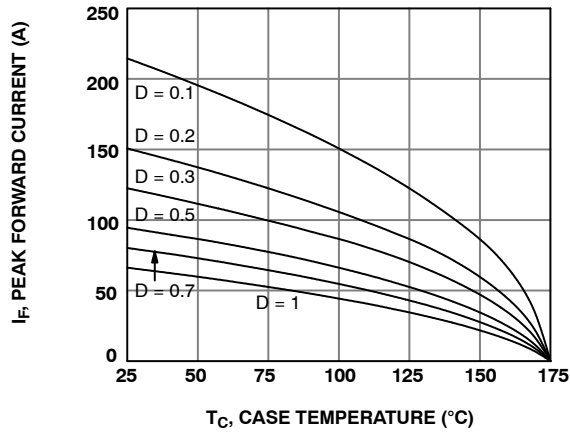


Figure 3. Current Derating

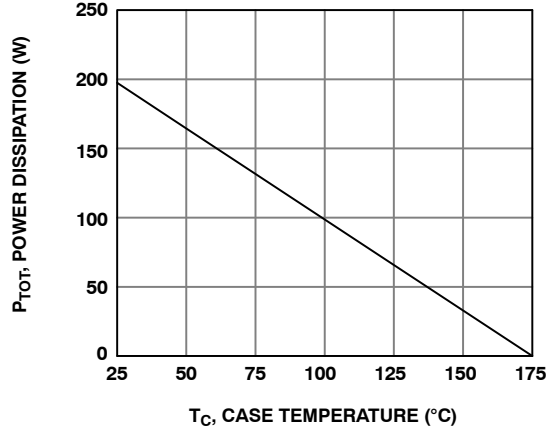


Figure 4. Power Dissipation

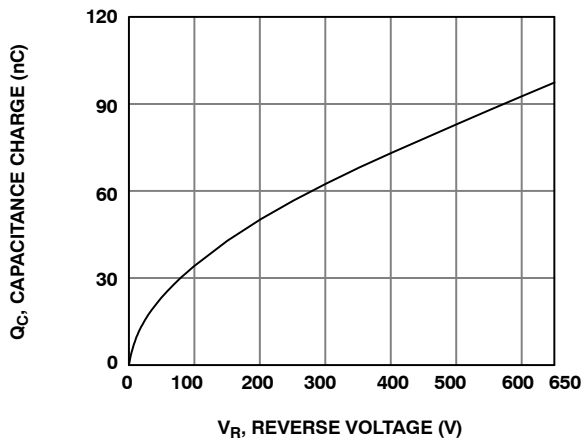


Figure 5. Capacitance Charge vs. Reverse Voltage

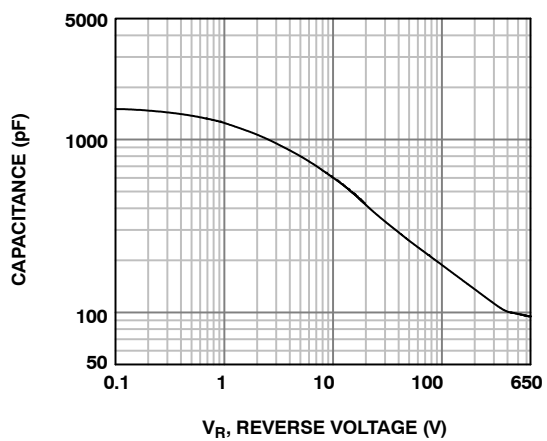


Figure 6. Capacitance vs. Reverse Voltage

# FFSP3065B

TYPICAL CHARACTERISTICS  $T_J = 25^\circ\text{C}$  UNLESS OTHERWISE NOTED (CONTINUED)

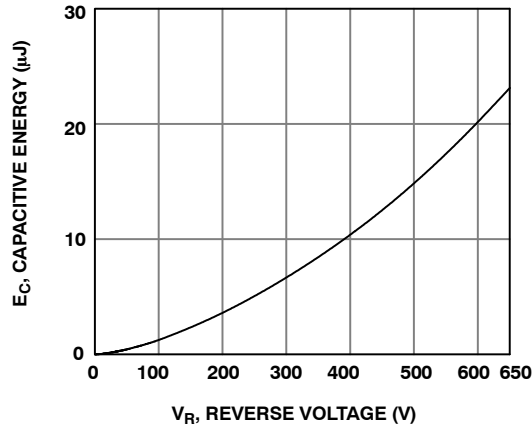


Figure 7. Capacitance Stored Energy

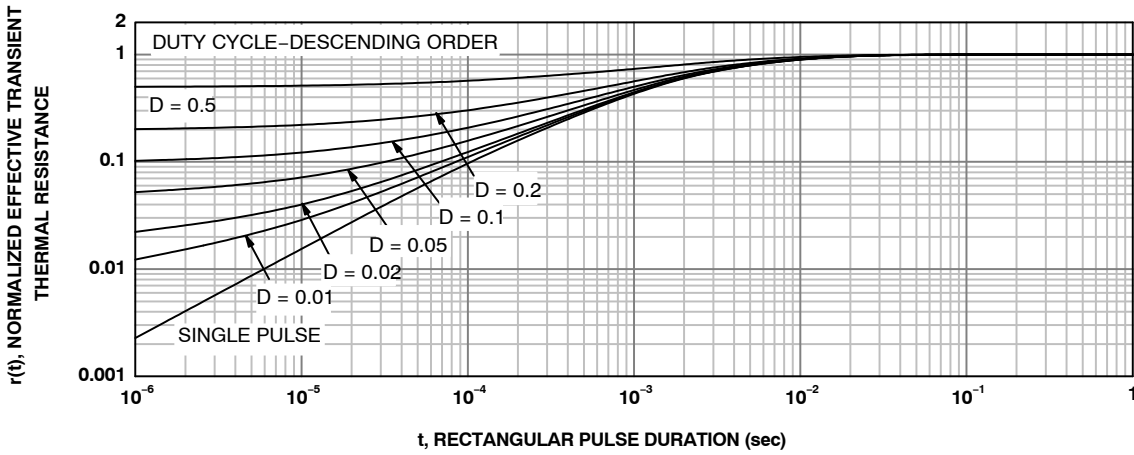


Figure 8. Junction-to-Case Transient Thermal Response Curve

## TEST CIRCUIT AND WAVEFORMS

$L = 0.5 \text{ mH}$   
 $R < 0.1 \Omega$   
 $V_{DD} = 50 \text{ V}$

$E_{AVL} = 1/2LI^2 [V_{R(AVL)}/(V_{R(AVL)} - V_{DD})]$   
 $Q1 = \text{IGBT (} BV_{CES} > DUT V_{R(AVL)} \text{)}$

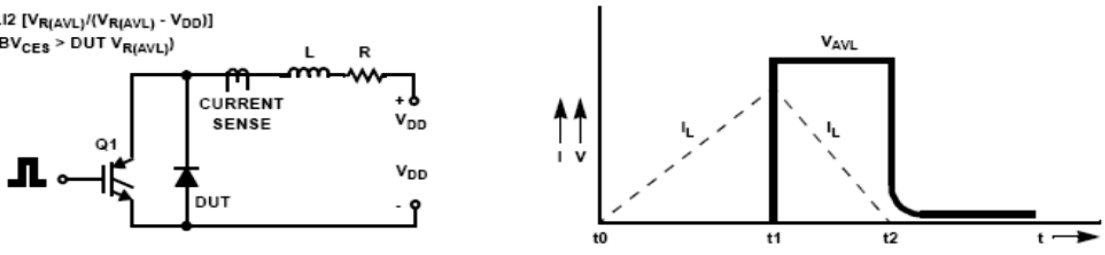


Figure 9. Unclamped Inductive Switching Test Circuit & Waveform

# MECHANICAL CASE OUTLINE

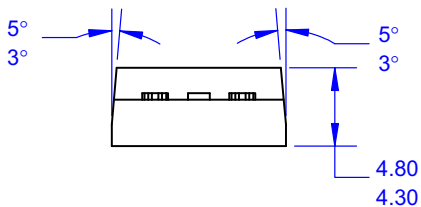
## PACKAGE DIMENSIONS

ON Semiconductor®



TO-220-2LD  
CASE 340BB  
ISSUE O

DATE 31 AUG 2016



### NOTES:

- A. PACKAGE REFERENCE: JEDEC TO220,ISSUE K, VARIATION AC, DATED APRIL 2002.
- B. ALL DIMENSIONS ARE IN MILLIMETERS.
- C. DIMENSION AND TOLERANCE AS PER ASME Y14.5-2009.
- D. DIMENSIONS ARE EXCLUSIVE OF BURRS, MOLD FLASH AND TIE BAR PROTRUSIONS.

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